

SOLDER MATERIALS

SOLDER WIRES

The Multicore® portfolio of cored solder wire features the award-winning multiple flux core technology that ensures the even and consistent distribution of flux throughout the solder wire. This mainstay in Henkel's line of solder products delivers ease of use and outstanding performance for today's delicate hand soldering assembly and rework operations.

Formulated with a variety of different alloy selections, Multicore® cored wires support traditional tin-lead manufacturing operations as well as modern lead-free processes. Our fast-wetting materials deliver excellent solder joint integrity and outstanding long-term performance.

SOLDER WIRES – NO CLEAN

PRODUCT	DESCRIPTION	ALLOY OPTIONS (Tin/Lead)	ALLOY OPTIONS* (LEAD FREE)	IPC/J-STD-004 CLASSIFICATION
MULTICORE® C400™	Halide-free, no-clean, clear residue, increased flux content for improved wetting.	SN62 60/40 63/37	SAC305 (97SC) SAC387 (96SC) 99C	ROLO
MULTICORE® C502™	No-clean, clear residue, medium activity flux with good wetting on difficult substrates.	SN62 60/40 63/37	SAC305 (97SC) SAC387 (96SC) 99C	ROM1

SOLDER WIRES – WATER WASH

PRODUCT	DESCRIPTION	SOLIDS CONTENT (%)	ACID VALUE (MG KOH/G)	IPC/J-STD-004 CLASSIFICATION
MULTICORE® Hydro-X™	High activity, water washable flux with excellent wetting on difficult substrates.	SN62 60/40 63/37	SAC305 (97SC) SAC387 (36SC) 99C	ORH1